



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Intel Corporation

Title:

COMPOSITE THERMAL INTERFACE DEVICES AND METHODS FOR
INTEGRATED CIRCUIT HEAT TRANSFER

Docket No.: 884.848US1

Serial No.: 10/608,405

Filed: June 26, 2003

Due Date: November 8, 2005

Examiner: Gregory Thompson

Group Art Unit: 2835

Customer No.: 21186

Confirmation No.: 8439

Commissioner for Patents

Notice of Allowance Date:

Attn: MAIL STOP ISSUE FEE

August 8, 2005

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the attached:

☒ A check in the amount of \$1400.00 to cover the Large Entity Issue Fee Payment.

☒ A check in the amount of \$300.00 to cover the Publication Fee Payment.

☒ A check in the amount of \$3.00 to cover the Extra Patent Copies Fee (1 copy).

☒ Issue Fee Transmittal (Form PTOL-85).

☒ 5 pages of Formal Drawings

☒ A return postcard.

Please charge any additional required fees for the Issue Fee Payment or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number: 21186

By

David C. Peterson

Reg. No. 47,857

DCP:CMG:cfh

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Attn – MAIL STOP ISSUE FEE, P.O. Box 1450, Alexandria, VA 22313-1450, on this 8th day of November, 2005.

Carolyn Hulsey

Name

Signature